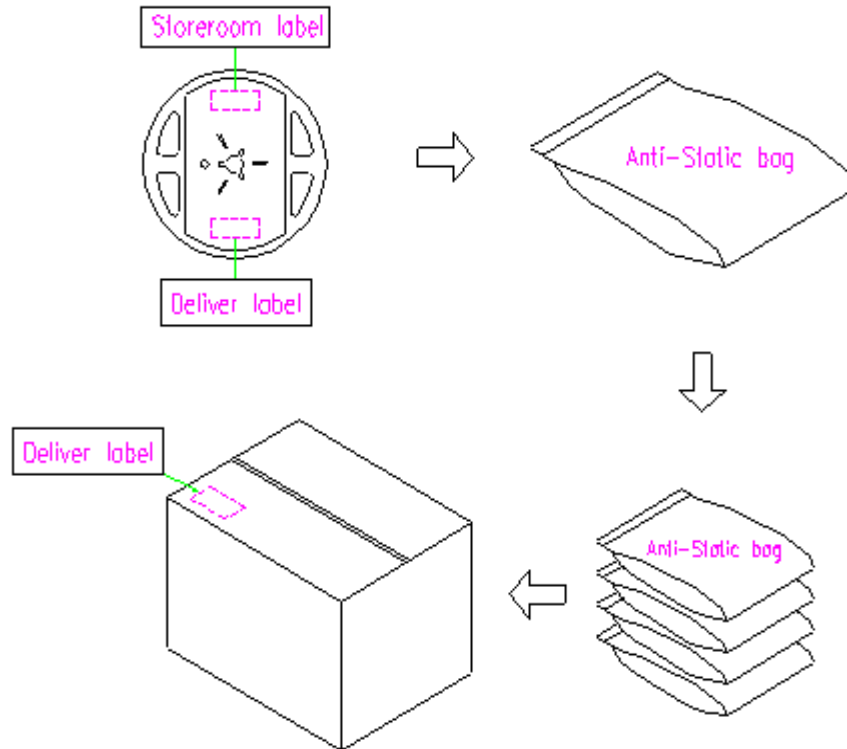


Preliminary

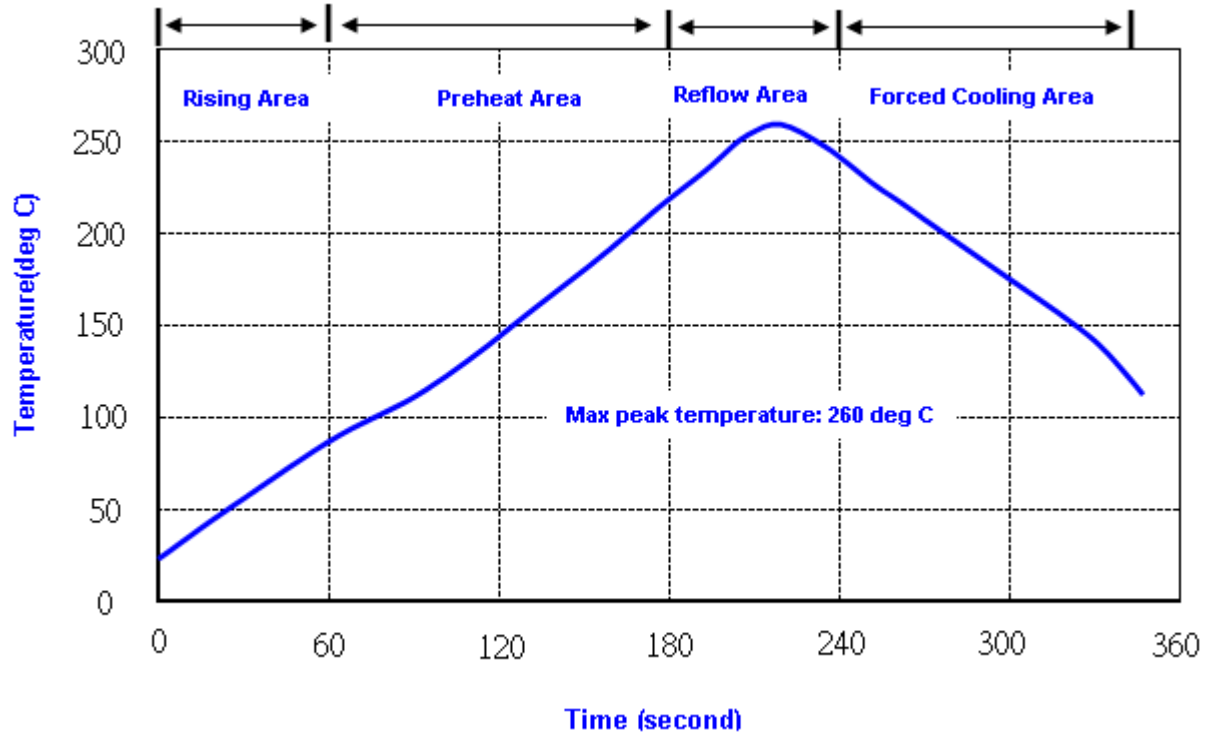


Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1. Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec
2. Temperature: 217+/-5 deg C; Time: 90~100 sec

Reliability Specifications

| Test name | Test process / method | Reference standard |
|--|--|-----------------------------------|
| Mechanical characteristics | | |
| resistance to Soldering heat (IR reflow) | Temp/ Duration : 265°C /10sec x2 times Total time : 4min.(IR-reflow) | EIAJED-4701 -300(301)M(II) |
| Vibration | Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc. | MIL-STD 202G method 204 |
| Mechanical Shock | directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine | MIL-STD 202G method 213 |
| Solderability | Solder Temperature:265±5 °C Duration time: 5±0.5 seconds. | J-STD-002 |
| Environmental characteristics | | |
| Thermal Shock | Heat cycle conditions -40 °C (30min) ↔ 85 °C (30min) * cycle time : 10 times | MIL-STD 883G method 1010.8 |
| Humidity test | Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours | MIL-STD 202G method 103 |
| Dry heat (Aging test) | Temperature : 125 ± 2 °C Duration : 168 hours | MIL-STD 202G method 108A |
| Cold resistance (Low Temp Storage) | Temperature : -40 ± 2 °C Duration : 96 hours | IEC 60068-2-1 |